



Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low capacitances
- Avalanche Ruggednes

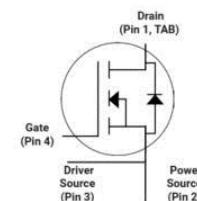


TO-263-7L
Package

Applications

- Solar Inverters
- Switch Mode Power Supplies
- Auxiliary power supplies
- Smart meters

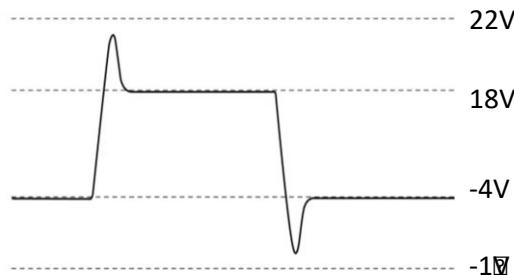
Ordering Part Number	Package	Marking
HC3M0075120J	TO-263-7L	H3007G7



Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	1200	V
Continuous drain current $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$	I_D	30 21	A
Source current(Body Diode) $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$	I_S	30 21	A
Pulsed drain current ($T_c = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D\text{ pulse}}$	80	A
Avalanche energy, single pulse ($L=10\text{mH}$)	E_{AS}	600	mJ
Gate-Source voltage	V_{GS}	-4/+18	V
Gate-Source voltage (dynamic,Absolute maximum values)	$V_{GS\text{max}}$	-8/+22	V
Power dissipation ($T_c = 25^\circ\text{C}$)	P_{tot}	136	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+175	°C

- Example of acceptable V_{GS} waveform





Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R _{thJC}	1.1	°C/W
Thermal resistance, junction – ambient. Max	R _{thJA}	40	

Electrical Characteristics (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristics						
Drain-source breakdown voltage	V _{DSS}	1200	-	-	V	V _{GS} =0V, I _D =100μA
Gate threshold voltage	V _{GS(th)}	2.3	2.8	3.6	V	V _{DS} =V _{GS} , I _D =5mA
Zero gate voltage drain current	I _{DSS}	-	1	10	μA	V _{DS} =1200V, V _{GS} =0V
		-	5	-		T _C =25°C
		-	-	-		T _C =175°C
Gate-source leakage current	I _{GSS}	-		100	nA	V _{GS} =18V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	75	85	mΩ	V _{GS} =18V, I _D =20A,
		-	125	-		T _J =25°C
		-	-	-		T _J =175°C
Transconductance	g _{fs}	-	10	-	S	V _{DS} =20V, I _D =20A
Dynamic Characteristics						
Input Capacitance	C _{iss}	-	920	-	pF	V _{DS} = 1000V V _{GS} = 0V T _J = 25°C V _{AC} = 25mV f = 1MHz
Output Capacitance	C _{oss}	-	57	-		
Reverse Transfer Capacitance	C _{rss}	-	3.9	-		
Gate Total Charge	Q _G	-	40	-	nC	V _{DS} = 800V V _{GS} = -4/18V I _D = 20A
Gate-Source charge	Q _{gs}	-	7	-		
Gate-Drain charge	Q _{gd}	-	19	-		
Turn-On Switching Energy	E _{ON}	-	320	-	μJ	V _{DD} = 800V V _{GS} = -4/+15V I _D = 20A R _G = 0Ω L = 120uH
Turn-Off Switching Energy	E _{OFF}	-	49	-		
Turn-on delay time	t _{d(on)}	-	19	-		
Rise time	t _r	-	21	-	ns	V _{DD} = 800V V _{GS} = -4/+15V I _D = 20A R _G = 0Ω L = 120uH
Turn-off delay time	t _{d(off)}	-	15	-		
Fall time	t _f	-	17	-		
Gate resistance	R _G	-	1.5	-	Ω	V _{AC} = 25mV, f=1MHz

**Body Diode Characteristics**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	4.2	-	V	$V_{GS}=-4V, I_{SD}=10A, T_J=25^{\circ}C$
		-	3.8	-		$V_{GS}=-4V, I_{SD}=10A, T_J=175^{\circ}C$
Body Diode Forward Current	I_{SD}	-	-	30	A	$V_{GS}=-4V, T_J=25^{\circ}C$ $V_R = 800V, V_{GS} = -4V I_D = 20A$ $di/dt = 700A/\mu S T_J = 25^{\circ}C$
Pulsed Body Diode Forward Current	I_{SDM}	-	-	89		
Reverse Recovery Time	t_{rr}	-	39.6	-		
Reverse Recovery Charge	Q_{rr}	-	141.1	-		
Reverse Recovery Energy	E_{REC}	-	62.9	-		
Peak Reverse Recovery Current	I_{rrm}	-	6.2	-		
Charge Time	t_A	-	9.9	-		
Discharge Time	t_B	-	29.7	-		
Reverse Recovery Time	t_{rr}	-	45.4	-		
Reverse Recovery Charge	Q_{rr}	-	397	-		
Reverse Recovery Energy	E_{REC}	-	180.1	-	A	$V_R = 800V, V_{GS} = -4V I_D = 20A$ $di/dt = 700A/\mu S T_J = 175^{\circ}C$
Peak Reverse Recovery Current	I_{rrm}	-	13.8	-		
Charge Time	t_A	-	30.8	-		
Discharge Time	t_B	-	14.9	-		



Typical Performance Characteristics

Fig 1. Output Characteristic ($T_J = -40^\circ\text{C}$)

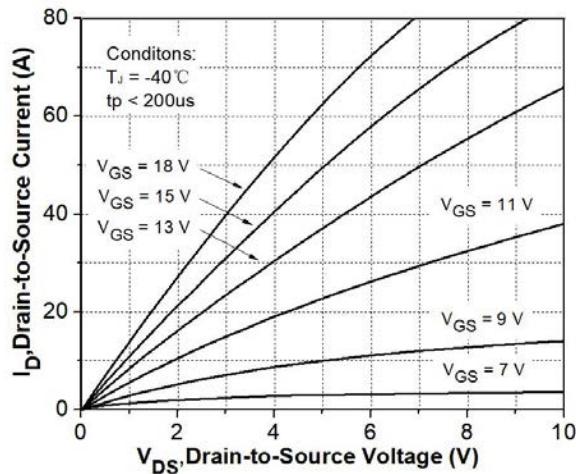


Fig 2. Output Characteristic ($T_J = 25^\circ\text{C}$)

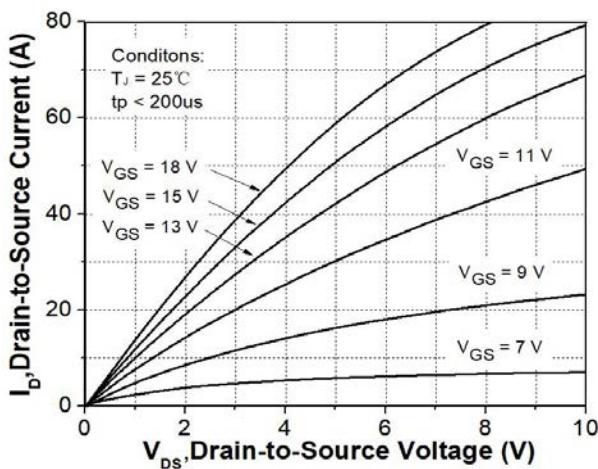


Fig 3. Output Characteristic ($T_J = 175^\circ\text{C}$)

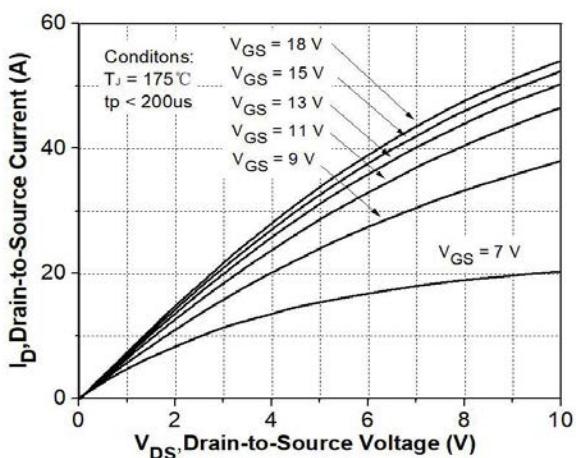


Fig 5: $R_{DS(on)}$ vs. Temperature

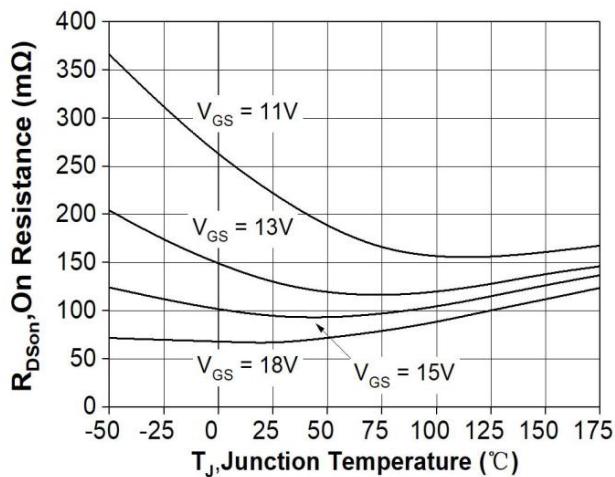


Fig 4: $R_{DS(on)}$ Vs I_{DS} Characteristic

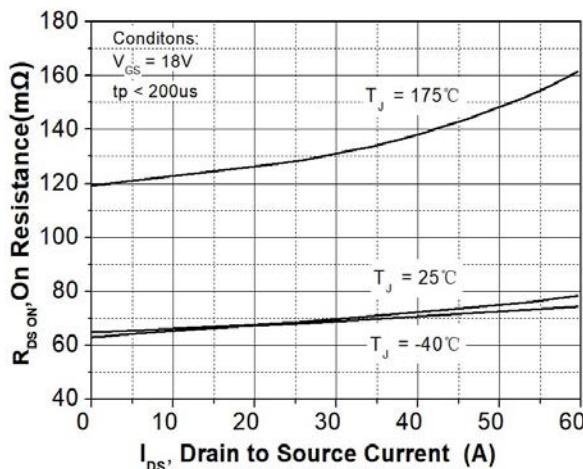


Fig 6: Transfer Characteristic

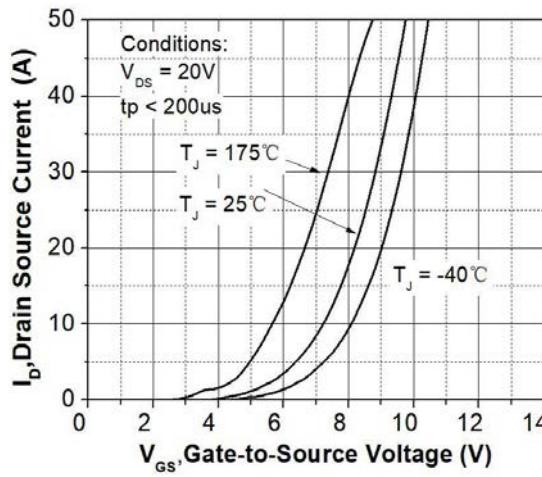




Fig 7: Body-diode Characteristic ($T_J = -40^\circ\text{C}$)

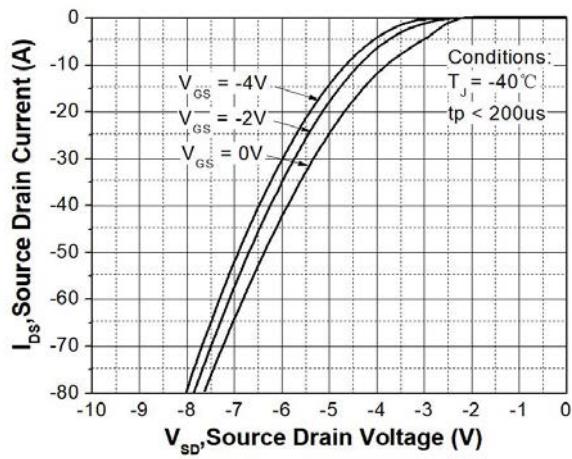


Fig 8: Body-diode Characteristic ($T_J = 25^\circ\text{C}$)

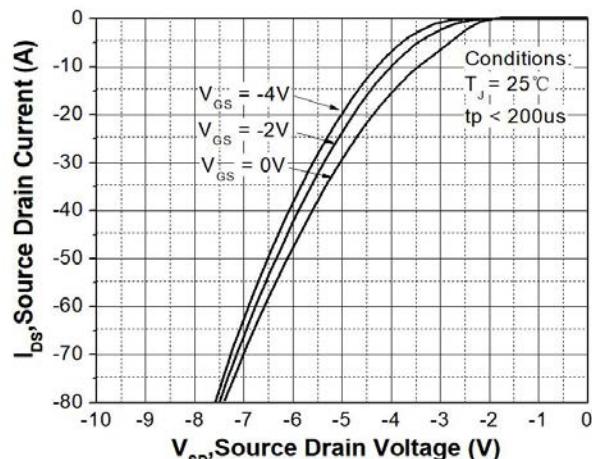


Fig 9: Body-diode Characteristic ($T_J = 175^\circ\text{C}$)

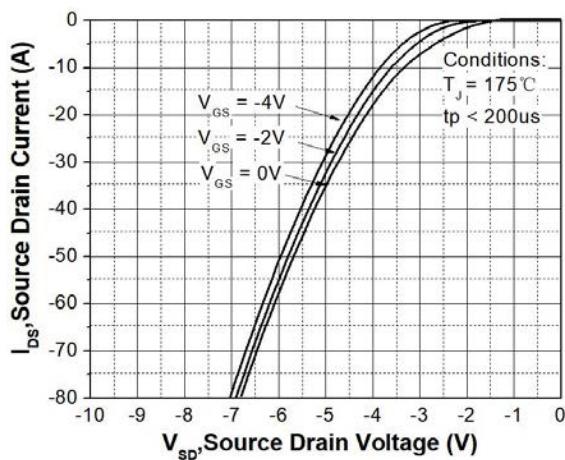


Fig 10: V_{TH} Vs T_J Temperature Characteristic

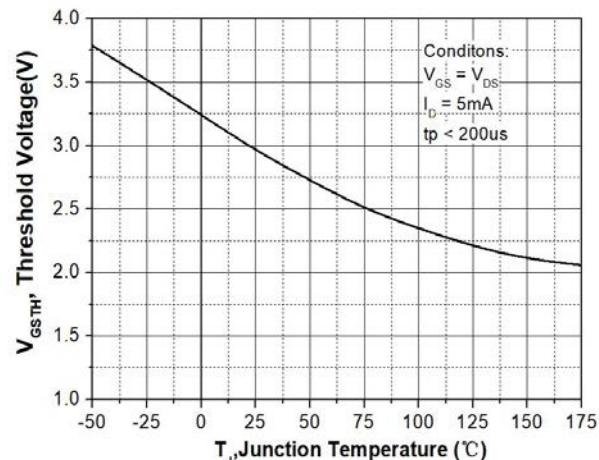


Fig 11: Gate Charge Characteristics

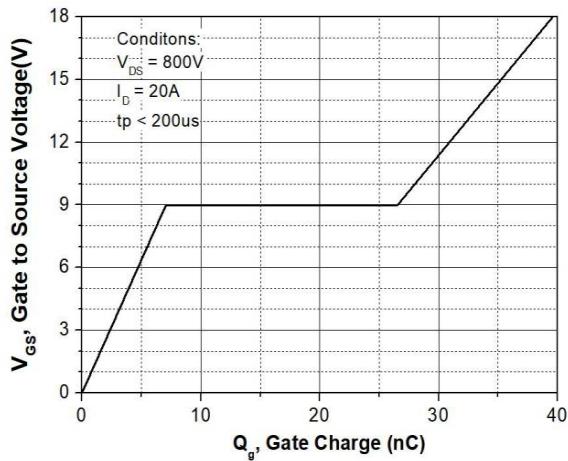


Fig 12: 3rd Quadrant Characteristic($T_J = -40^\circ\text{C}$)

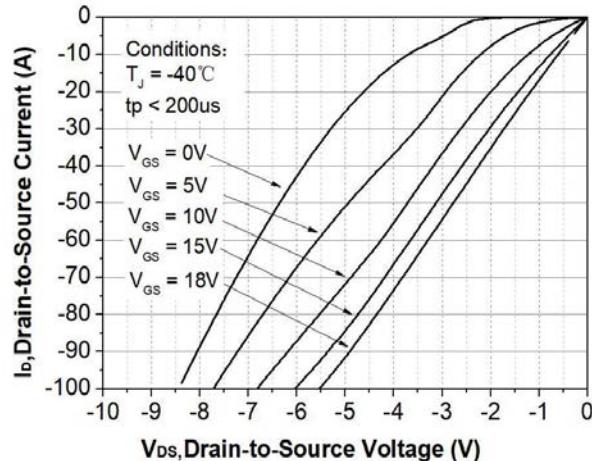




Fig 13: 3rd Quadrant Characteristic($T_J=25^\circ\text{C}$)

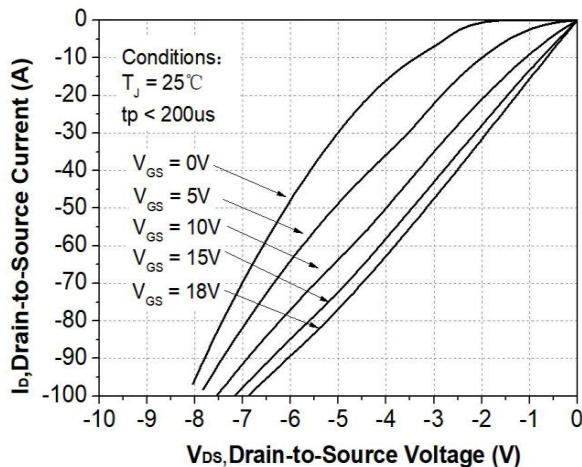


Fig 14: 3rd Quadrant Characteristic($T_J=175^\circ\text{C}$)

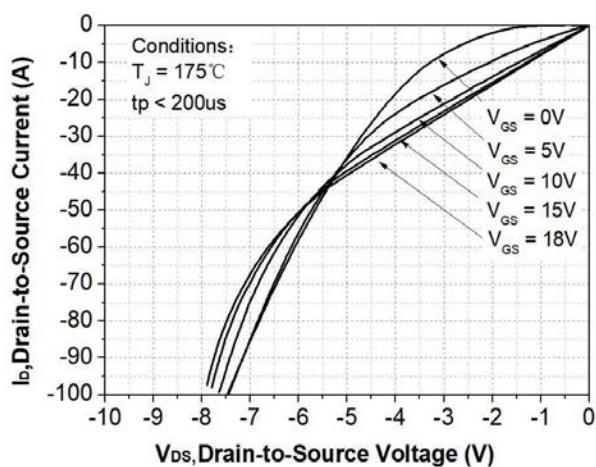


Fig 15: Capacitance Characteristic

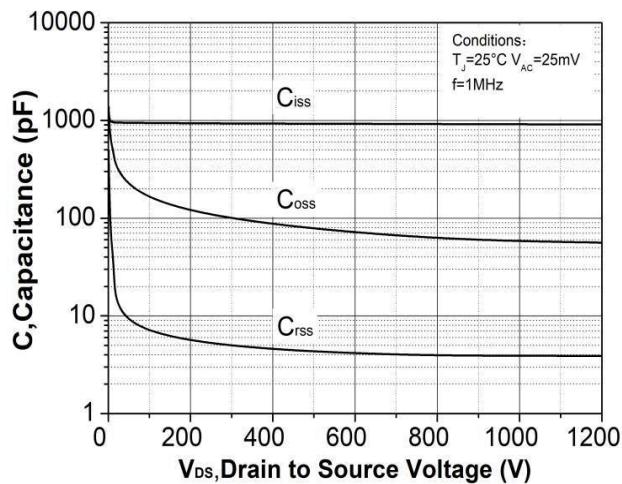


Fig 16: Safe Operating Area

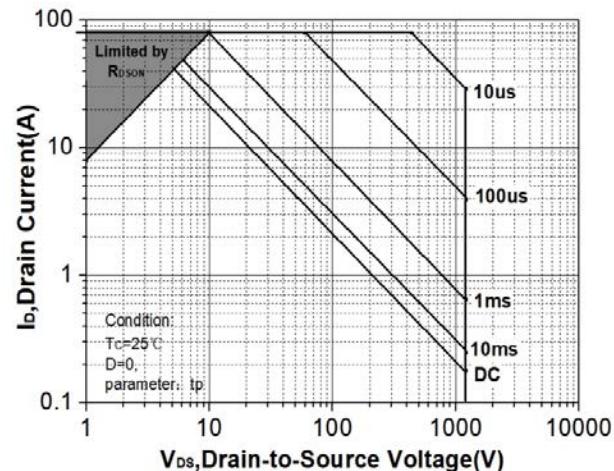
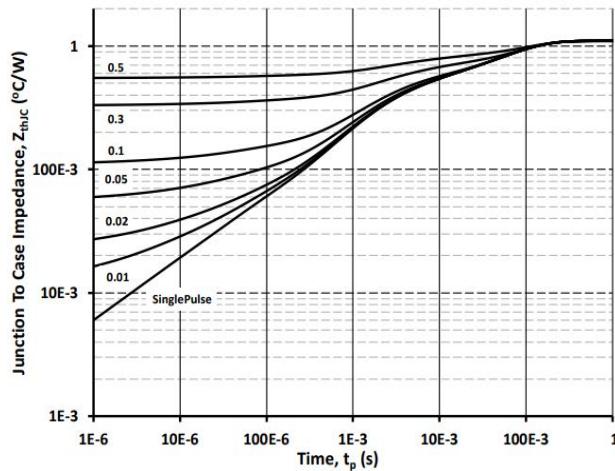


Fig 17: Transient Thermal Impedance





Test Circuit Schematic

Figure A. Definition of switching times

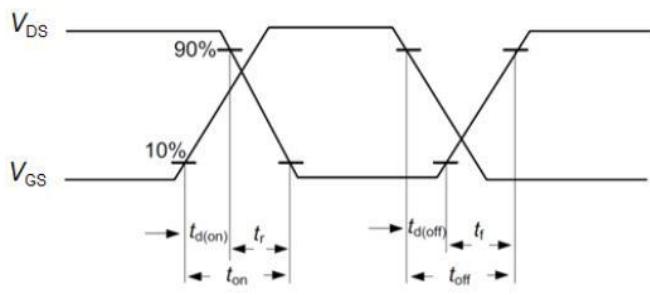


Figure B. Dynamic test circuit

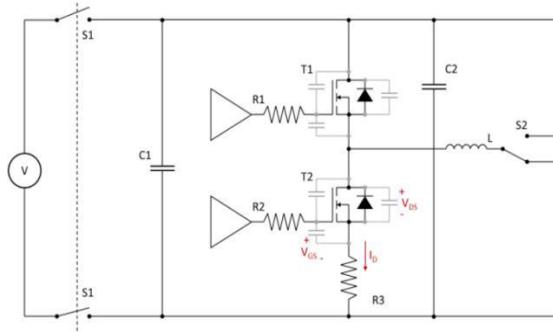


Figure C. Definition of body diodeswitching characteristics

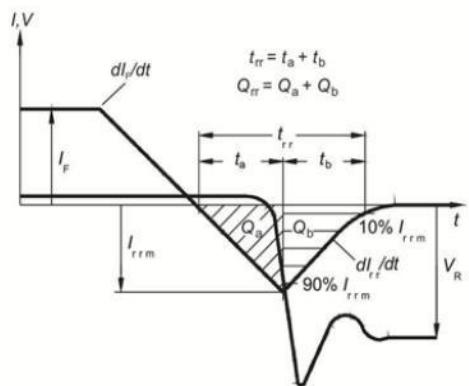
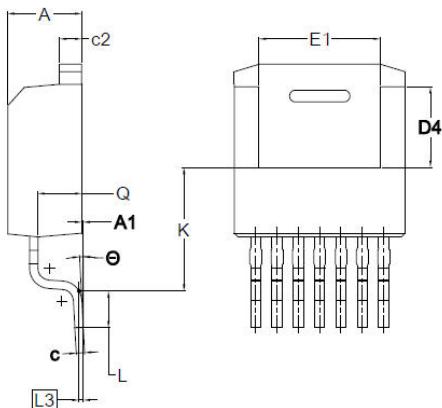
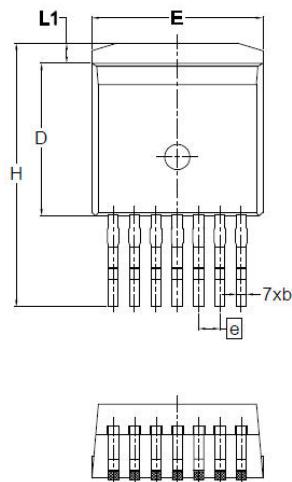


Figure C. Definition of diode switching characteristics



Package Dimensions

Package TO-263-7L



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.30	4.40	4.50
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
c	0.45	0.50	0.60
c2	1.20	1.30	1.40
D	8.93	9.08	9.23
D4	4.65	4.80	4.95
E	10.08	10.18	10.28
E1	6.82	7.22	7.62
e	1.27 BSC		
H	15.00	15.70	16.00
K	7.30		
L	1.90	2.20	2.50
L1	1.00	1.20	1.40
L3	0.25 BSC		
Q	2.45	2.60	2.75
Θ	0°	3°	7°



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